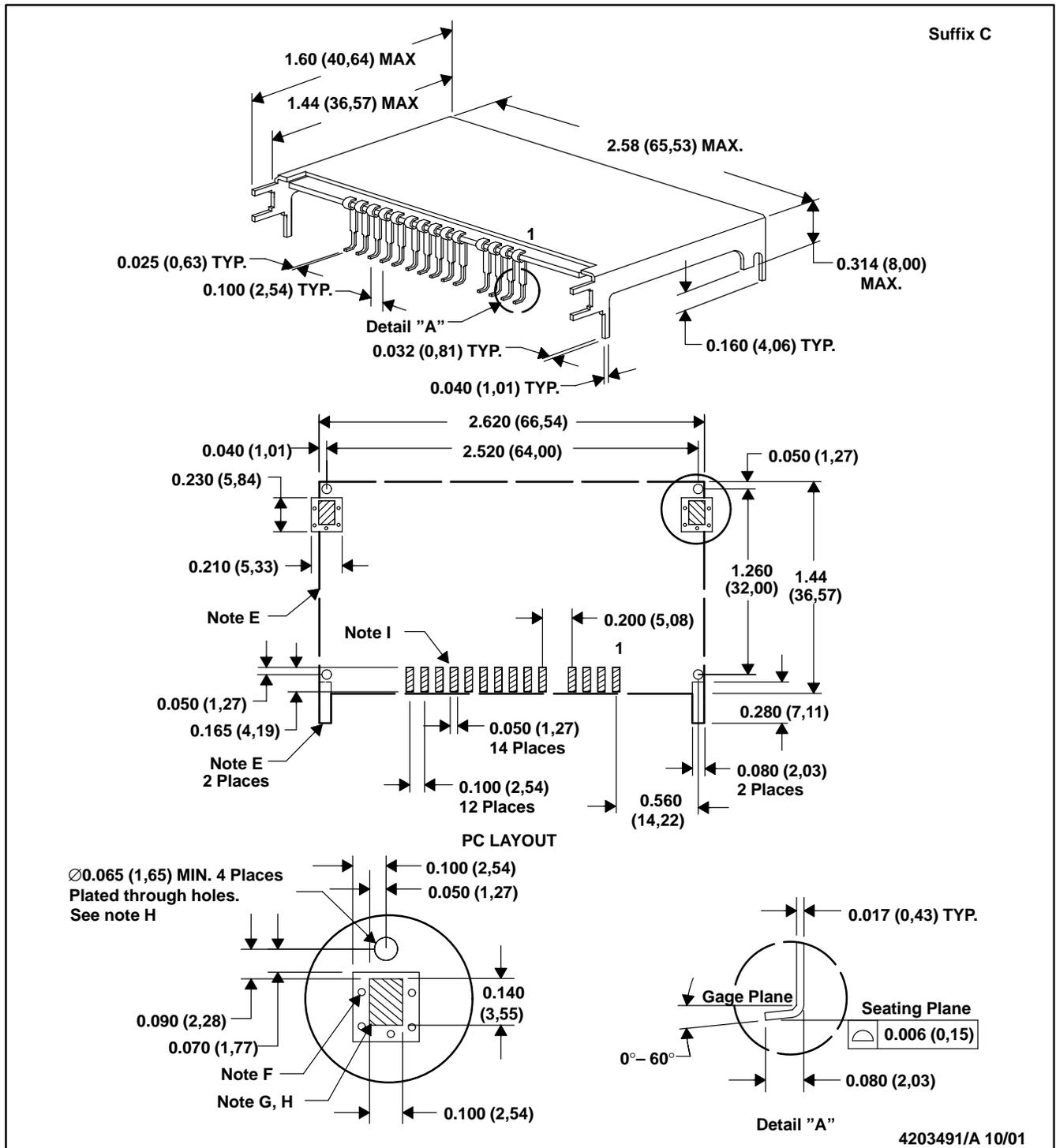


EPN (R-MSIP-G14)

METAL SINGLE-IN-LINE MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
  - B. This drawing is subject to change without notice.
  - C. 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - D. 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - E. Recommended mechanical keep out area.
  - F. Vias are recommended to improve copper adhesion.
  - G. Solder mask openings to copper island for solder joints to mechanical pins.
  - H. The case is electrically uncommitted. The recommended connection is to secondary ground.
  - I. Power pin connections should utilize two or more vias per input, ground and output pin.

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